



**A405 GPP Axial-leaded Rectifier**

<b>Material Content Declaration</b>					
<b>Material name</b>	<b>Substance name, e.g. Copper (Cu).</b>	<b>CAS no., if known</b>	<b>Substance mass (mg)</b>	<b>% OF Weight (%)</b>	<b>ppm Of Total Weight</b>
<b>Lead Wire 58.51%</b>	Copper (Cu)	7440-50-8	166.4667	99.9787	584,957.6
	Phosphorus (P)	7723-14-0	0.0017	0.0010	5.9
	Arsenic (As)	7440-38-2	0.0017	0.0010	5.9
	Tin (Sn)	7440-31-5	0.0017	0.0010	5.9
	Oxygen (O)	7782-44-7	0.0008	0.0005	2.9
	Sulfur (S)	7704-34-9	0.0200	0.0120	70.2
	Iron (Fe)	7439-89-6	0.0011	0.0007	3.9
	Nickel (Ni)	7440-02-0	0.0005	0.0003	1.8
	Bismuth (Bi)	7440-69-9	0.0033	0.0020	11.7
	Antimony (Sb)	1309-64-4	0.0033	0.0020	11.7
	Lead (Pb)	7439-92-1	0.0008	0.0005	2.9
	Zinc (Zn)	7440-66-6	0.0005	0.0003	1.8
	<b>Total</b>		<b>166.50</b>		
<b>Solder Wafer 0.69%</b>	Lead (Pb)	7439-92-1	1.829	92.51	6,427.0
	Tin (Sn)	7440-31-5	0.099	5.01	347.9
	Silver (Ag)	7440-22-4	0.049	2.48	172.2
	<b>Total</b>		<b>1.98</b>		
<b>Chip 1.22%</b>	Silicon (Si)	7440-21-3	3.30	95.40	11,599.0
	Lead (Pb)	7439-92-1	0.16	4.60	559.3
	<b>Total</b>		<b>3.46</b>		
<b>Molding 39.26%</b>	Epoxy	38891-59-7	111.74	100.00	392,650.1
	<b>Total</b>		<b>111.74</b>		
<b>Plating 0.32%</b>	Tin (Sn)	7440-31-5	0.9	100.00	3,162.6
	<b>Total</b>		<b>0.90</b>		
	<b>Total mass (mg)</b>		<b>284.58</b>		